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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	CANbus, EBI/EMI, I²C, IrDA, LINbus, MMC/SD, QSPI, SAI, SPI, SWPMI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, PWM, WDT
Number of I/O	109
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 19x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	132-UFBGA
Supplier Device Package	132-UFBGA (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/stm32l471qgi6

By default, the microcontroller is in Run mode after a system or a power Reset. It is up to the user to select one of the low-power modes described below:

- **Sleep** mode

  In Sleep mode, only the CPU is stopped. All peripherals continue to operate and can wake up the CPU when an interrupt/event occurs.

- **Low-power run** mode

  This mode is achieved with VCORE supplied by the low-power regulator to minimize the regulator's operating current. The code can be executed from SRAM or from Flash, and the CPU frequency is limited to 2 MHz. The peripherals with independent clock can be clocked by HSI16.

- **Low-power sleep** mode

  This mode is entered from the low-power run mode. Only the CPU clock is stopped. When wakeup is triggered by an event or an interrupt, the system reverts to the low-power run mode.

- **Stop 0, Stop 1 and Stop 2** modes

  Stop mode achieves the lowest power consumption while retaining the content of SRAM and registers. All clocks in the VCORE domain are stopped, the PLL, the MSI RC, the HSI16 RC and the HSE crystal oscillators are disabled. The LSE or LSI is still running.

  The RTC can remain active (Stop mode with RTC, Stop mode without RTC).

  Some peripherals with wakeup capability can enable the HSI16 RC during Stop mode to detect their wakeup condition.

  Three Stop modes are available: Stop 0, Stop 1 and Stop 2 modes. In Stop 2 mode, most of the VCORE domain is put in a lower leakage mode.

  Stop 1 offers the largest number of active peripherals and wakeup sources, a smaller wakeup time but a higher consumption than Stop 2. In Stop 0 mode, the main regulator remains ON, allowing a very fast wakeup time but with much higher consumption.

  The system clock when exiting from Stop 0, Stop1 or Stop2 modes can be either MSI up to 48 MHz or HSI16, depending on software configuration.

- **Standby** mode

  The Standby mode is used to achieve the lowest power consumption with BOR. The internal regulator is switched off so that the VCORE domain is powered off. The PLL, the MSI RC, the HSI16 RC and the HSE crystal oscillators are also switched off.

  The RTC can remain active (Standby mode with RTC, Standby mode without RTC).

  The brown-out reset (BOR) always remains active in Standby mode.

  The state of each I/O during standby mode can be selected by software: I/O with internal pull-up, internal pull-down or floating.

  After entering Standby mode, SRAM1 and register contents are lost except for registers in the Backup domain and Standby circuitry. Optionally, SRAM2 can be retained in

3.27 Low-power universal asynchronous receiver transmitter (LPUART)

The device embeds one Low-Power UART. The LPUART supports asynchronous serial communication with minimum power consumption. It supports half duplex single wire communication and modem operations (CTS/RTS). It allows multiprocessor communication.

The LPUART has a clock domain independent from the CPU clock, and can wakeup the system from Stop mode. The wake up events from Stop mode are programmable and can be:

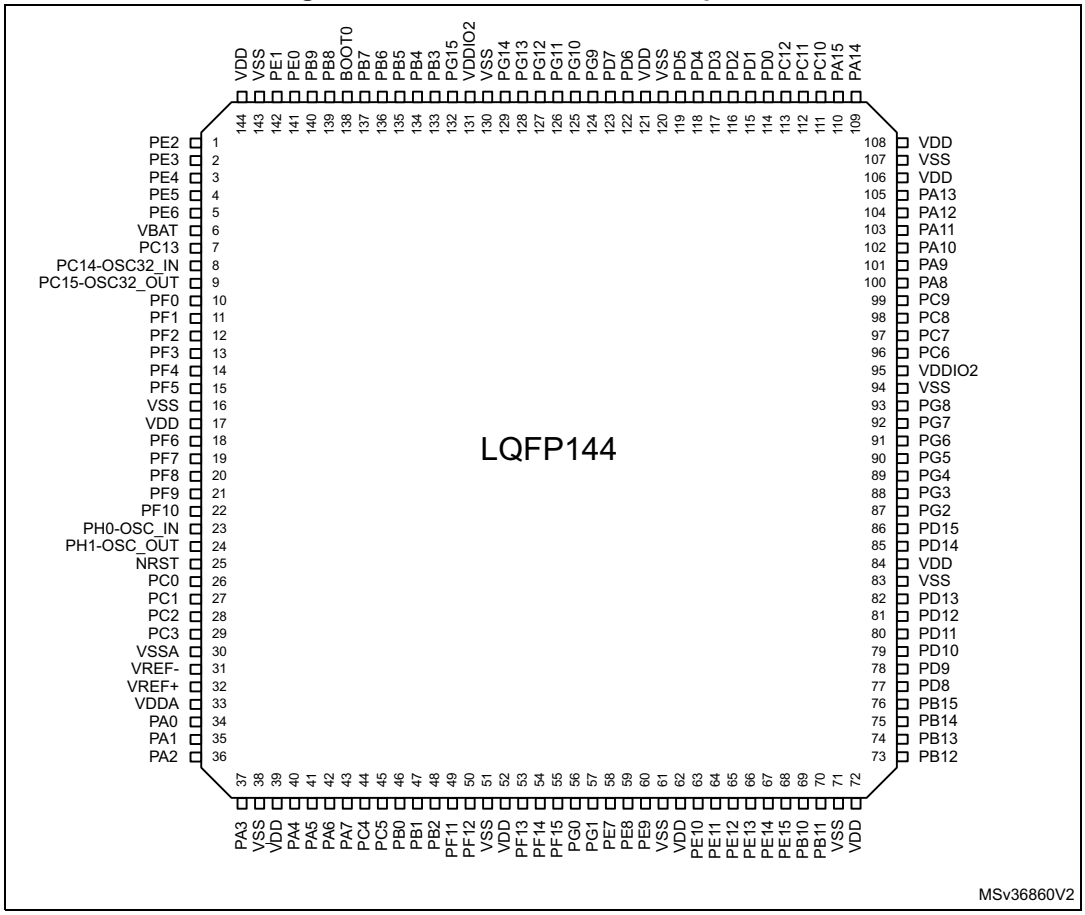
- Start bit detection
- Any received data frame
- A specific programmed data frame

Only a 32.768 kHz clock (LSE) is needed to allow LPUART communication up to 9600 baud. Therefore, even in Stop mode, the LPUART can wait for an incoming frame while having an extremely low energy consumption. Higher speed clock can be used to reach higher baudrates.

LPUART interface can be served by the DMA controller.

4 Pinouts and pin description

Figure 5. STM32L471Zx LQFP144 pinout(1)



1. The above figure shows the package top view.

Table 15. STM32L471xx pin definitions (continued)

Pin Number				Pin name (function after reset)	Pin type	I/O structure	Notes	Pin functions	
LQFP64	LQFP100	UFBGA132	LQFP144					Alternate functions	Additional functions
25	34	L5	45	PC5	I/O	FT_a	-	USART3_RX, EVENTOUT	COMP1_INP, ADC12_IN14, WKUP5
26	35	M5	46	PB0	I/O	TT_a	-	TIM1_CH2N, TIM3_CH3, TIM8_CH2N, USART3_CK, QUADSPI_BK1_IO1, COMP1_OUT, EVENTOUT	OPAMP2_ VOUT, ADC12_IN15
27	36	M6	47	PB1	I/O	FT_a	-	TIM1_CH3N, TIM3_CH4, TIM8_CH3N, DFSDM_DATIN0, USART3_RTS_DE, QUADSPI_BK1_IO0, LPTIM2_IN1, EVENTOUT	COMP1_INM, ADC12_IN16
28	37	L6	48	PB2	I/O	FT_a	-	RTC_OUT, LPTIM1_OUT, I2C3_SMBA, DFSDM_CKIN0, EVENTOUT	COMP1_INP
-	-	K6	49	PF11	I/O	FT	-	EVENTOUT	-
-	-	J7	50	PF12	I/O	FT	-	FMC_A6, EVENTOUT	-
-	-	-	51	VSS	S	-	-	-	-
-	-	-	52	VDD	S	-	-	-	-
-	-	K7	53	PF13	I/O	FT	-	DFSDM_DATIN6, FMC_A7, EVENTOUT	-
-	-	J8	54	PF14	I/O	FT	-	DFSDM_CKIN6, TSC_G8_IO1, FMC_A8, EVENTOUT	-
-	-	J9	55	PF15	I/O	FT	-	TSC_G8_IO2, FMC_A9, EVENTOUT	-
-	-	H9	56	PG0	I/O	FT	-	TSC_G8_IO3, FMC_A10, EVENTOUT	-
-	-	G9	57	PG1	I/O	FT	-	TSC_G8_IO4, FMC_A11, EVENTOUT	-
-	38	M7	58	PE7	I/O	FT	-	TIM1_ETR, DFSDM_DATIN2, FMC_D4, SAI1_SD_B, EVENTOUT	-
-	39	L7	59	PE8	I/O	FT	-	TIM1_CH1N, DFSDM_CKIN2, FMC_D5, SAI1_SCK_B, EVENTOUT	-

Table 16. Alternate function AF0 to AF7 (for AF8 to AF15 see *Table 17*)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7
		SYS_AF	TIM1/TIM2/ TIM5/TIM8/ LPTIM1	TIM1/TIM2/ TIM3/TIM4/ TIM5	TIM8	I2C1/I2C2/I2C3	SPI1/SPI2	SPI3/DFSDM	USART1/ USART2/ USART3
Port A	PA0	-	TIM2_CH1	TIM5_CH1	TIM8_ETR	-	-	-	USART2_CTS
	PA1	-	TIM2_CH2	TIM5_CH2	-	-	-	-	USART2_RTS_ DE
	PA2	-	TIM2_CH3	TIM5_CH3	-	-	-	-	USART2_TX
	PA3	-	TIM2_CH4	TIM5_CH4	-	-	-	-	USART2_RX
	PA4	-	-	-	-	-	SPI1_NSS	SPI3_NSS	USART2_CK
	PA5	-	TIM2_CH1	TIM2_ETR	TIM8_CH1N	-	SPI1_SCK	-	-
	PA6	-	TIM1_BKIN	TIM3_CH1	TIM8_BKIN	-	SPI1_MISO	-	USART3_CTS
	PA7	-	TIM1_CH1N	TIM3_CH2	TIM8_CH1N	-	SPI1_MOSI	-	-
	PA8	MCO	TIM1_CH1	-	-	-	-	-	USART1_CK
	PA9	-	TIM1_CH2	-	-	-	-	-	USART1_TX
	PA10	-	TIM1_CH3	-	-	-	-	-	USART1_RX
	PA11	-	TIM1_CH4	TIM1_BKIN2	-	-	-	-	USART1_CTS
	PA12	-	TIM1_ETR	-	-	-	-	-	USART1_RTS_ DE
	PA13	JTMS-SWDIO	IR_OUT	-	-	-	-	-	-
	PA14	JTCK-SWCLK	-	-	-	-	-	-	-
	PA15	JTDI	TIM2_CH1	TIM2_ETR	-	-	SPI1_NSS	SPI3_NSS	-

Table 16. Alternate function AF0 to AF7 (for AF8 to AF15 see *Table 17*) (continued)

Port		AF0	AF1	AF2	AF3	AF4	AF5	AF6	AF7
		SYS_AF	TIM1/TIM2/ TIM5/TIM8/ LPTIM1	TIM1/TIM2/ TIM3/TIM4/ TIM5	TIM8	I2C1/I2C2/I2C3	SPI1/SPI2	SPI3/DFSDM	USART1/ USART2/ USART3
Port D	PD0	-	-	-	-	-	SPI2_NSS	DFSDM_DATIN7	-
	PD1	-	-	-	-	-	SPI2_SCK	DFSDM_CKIN7	-
	PD2	-	-	TIM3_ETR	-	-	-	-	USART3_RTS_ DE
	PD3	-	-	-	-	-	SPI2_MISO	DFSDM_DATIN0	USART2_CTS
	PD4	-	-	-	-	-	SPI2_MOSI	DFSDM_CKIN0	USART2_RTS_ DE
	PD5	-	-	-	-	-	-	-	USART2_TX
	PD6	-	-	-	-	-	-	DFSDM_DATIN1	USART2_RX
	PD7	-	-	-	-	-	-	DFSDM_CKIN1	USART2_CK
	PD8	-	-	-	-	-	-	-	USART3_TX
	PD9	-	-	-	-	-	-	-	USART3_RX
	PD10	-	-	-	-	-	-	-	USART3_CK
	PD11	-	-	-	-	-	-	-	USART3_CTS
	PD12	-	-	TIM4_CH1	-	-	-	-	USART3_RTS_ DE
	PD13	-	-	TIM4_CH2	-	-	-	-	-
	PD14	-	-	TIM4_CH3	-	-	-	-	-
	PD15	-	-	TIM4_CH4	-	-	-	-	-

6.3 Operating conditions

6.3.1 General operating conditions

Table 22. General operating conditions

Symbol	Parameter	Conditions		Min	Max	Unit
f_{HCLK}	Internal AHB clock frequency	-		0	80	MHz
f_{PCLK1}	Internal APB1 clock frequency	-		0	80	
f_{PCLK2}	Internal APB2 clock frequency	-		0	80	
V_{DD}	Standard operating voltage	-		1.71 (1)	3.6	V
V_{DDIO2}	PG[15:2] I/Os supply voltage	At least one I/O in PG[15:2] used		1.08	3.6	V
		PG[15:2] not used		0	3.6	
V_{DDA}	Analog supply voltage	ADC or COMP used		1.62	3.6	V
		DAC or OPAMP used		1.8		
		VREFBUF used		2.4		
		ADC, DAC, OPAMP, COMP, VREFBUF not used		0		
V_{BAT}	Backup operating voltage	-		1.55	3.6	V
V_{IN}	I/O input voltage	TT_xx I/O		-0.3	V_{DDIOx}+0.3	V
		BOOT0		0	9	
		All I/O except BOOT0 and TT_xx		-0.3	MIN(MIN(V_{DD}, V_{DDA}, V_{DDIO2})+3.6 V, 5.5 V)(2)(3)	
P_D	Power dissipation at T_A = 85 °C for suffix 6 or T_A = 105 °C for suffix 7(4)	LQFP144	-	-	625	mW
		LQFP100	-	-	476	
		LQFP64	-	-	444	
		UFBGA132	-	-	363	
T_A	Ambient temperature for the suffix 6 version	Maximum power dissipation		–40	85	°C
		Low-power dissipation(5)		–40	105	
	Ambient temperature for the suffix 7 version	Maximum power dissipation		–40	105	
		Low-power dissipation(5)		–40	125	
	Ambient temperature for the suffix 3 version	Maximum power dissipation		–40	125	
		Low-power dissipation(5)		–40	130	
T_J	Junction temperature range	Suffix 6 version		–40	105	°C
		Suffix 7 version		–40	125	
		Suffix 3 version		–40	130	

1. When RESET is released functionality is guaranteed down to V_{BOR0} Min.
2. This formula has to be applied only on the power supplies related to the IO structure described by the pin definition table. Maximum I/O input voltage is the smallest value between MIN(V_{DD}, V_{DDA}, V_{DDIO2})+3.6 V and 5.5V.

Table 37. Current consumption in Standby mode (continued)

Symbol	Parameter	Conditions		TYP					MAX(1)					Unit
		-	V_{DD}	25 °C	55 °C	85 °C	105 °C	125 °C	25 °C	55 °C	85 °C	105 °C	125 °C	
I_{DD}(SRAM2) (4)	Supply current to be added in Standby mode when SRAM2 is retained	-	1.8 V	235	641	2293	5192	11213	588	1603	5733	12980	28033	nA
			2.4 V	237	645	2303	5213	11246	593	1613	5758	13033	28115	
			3 V	236	647	2306	5221	11333	593	1618	5765	13053	28333	
			3.6 V	235	646	2308	5200	11327	595	1620	5770	13075	28350	
I_{DD}(wakeup from Standby)	Supply current during wakeup from Standby mode	Wakeup clock is MSI = 4 MHz. See (5).	3 V	1.7	-	-	-	-	-					mA

1. Guaranteed by characterization results, unless otherwise specified.
2. Guaranteed by test in production.
3. Based on characterization done with a 32.768 kHz crystal (MC306-G-06Q-32.768, manufacturer JFVNY) with two 6.8 pF loading capacitors.
4. The supply current in Standby with SRAM2 mode is: I_{DD}(Standby) + I_{DD}(SRAM2). The supply current in Standby with RTC with SRAM2 mode is: I_{DD}(Standby + RTC) + I_{DD}(SRAM2).
5. Wakeup with code execution from Flash. Average value given for a typical wakeup time as specified in *Table 41: Low-power mode wakeup timings*.

Table 38. Current consumption in Shutdown mode

Symbol	Parameter	Conditions		TYP					MAX(1)					Unit
		-	V_{DD}	25 °C	55 °C	85 °C	105 °C	125 °C	25 °C	55 °C	85 °C	105 °C	125 °C	
I_{DD}(Shutdown)	Supply current in Shutdown mode (backup registers retained) RTC disabled	-	1.8 V	29.8	194	1110	3250	9093	75	485	2775	8125	22733	nA
			2.4 V	44.3	237	1310	3798	10473	111	593	3275	9495	26183	
			3 V	64.1	293	1554	4461	12082	160	733	3885	11153	30205	
			3.6 V	112	420	2041	5689	15186	280	1050	5103	14223	37965	

Table 39. Current consumption in VBAT mode

Symbol	Parameter	Conditions		TYP					MAX(1)					Unit
		-	V_{BAT}	25 °C	55 °C	85 °C	105 °C	125 °C	25 °C	55 °C	85 °C	105 °C	125 °C	
I_{DD}(VBAT)	Backup domain supply current	RTC disabled	1.8 V	4	29	196	587	1663	10.8	73	490	1468	4158	nA
			2.4 V	5.27	36	226	673	1884	13.2	90	565	1683	4710	
			3 V	6	42	264	775	2147	15.5	106	660	1938	5368	
			3.6 V	10	58	323	919	2488	25.8	144	808	2298	6220	
		RTC enabled and clocked by LSE bypassed at 32768 Hz	1.8 V	183	201	367	729	-	-	-	-	-	-	
			2.4 V	268	295	486	901	-	-	-	-	-	-	
			3 V	376	412	602	1075	-	-	-	-	-	-	
			3.6 V	508	558	752	1299	-	-	-	-	-	-	
		RTC enabled and clocked by LSE quartz(2)	1.8 V	302	344	521	915	1978	-	-	-	-	-	
			2.4 V	388	436	639	1091	2289	-	-	-	-	-	
			3 V	494	549	784	1301	2656	-	-	-	-	-	
			3.6 V	630	692	971	1571	3115	-	-	-	-	-	

1. Guaranteed by characterization results, unless otherwise specified.
2. Based on characterization done with a 32.768 kHz crystal (MC306-G-06Q-32.768, manufacturer JFVNY) with two 6.8 pF loading capacitors.

Table 40. Peripheral current consumption (continued)

Peripheral		Range 1	Range 2	Low-power run and sleep	Unit
APB1	USART2 independent clock domain	4.1	3.6	3.8	µA/MHz
	USART2 APB clock domain	1.4	1.1	1.5	
	USART3 independent clock domain	4.7	4.1	4.2	
	USART3 APB clock domain	1.5	1.3	1.7	
	UART4 independent clock domain	3.9	3.2	3.5	
	UART4 APB clock domain	1.5	1.3	1.6	
	UART5 independent clock domain	3.9	3.2	3.5	
	UART5 APB clock domain	1.3	1.2	1.4	
	WWDG	0.5	0.5	0.5	
	All APB1 on	84.2	70.7	80.2	
APB2	AHB to APB2 bridge(4)	1.0	0.9	0.9	
	DFSDM	5.6	4.6	5.3	
	FW	0.7	0.5	0.7	
	SAI1 independent clock domain	2.6	2.1	2.3	
	SAI1 APB clock domain	2.1	1.8	2.0	
	SAI2 independent clock domain	3.3	2.7	3.0	
	SAI2 APB clock domain	2.4	2.1	2.2	
	SDMMC1 independent clock domain	4.7	3.9	4.2	
	SDMMC1 APB clock domain	2.5	1.9	2.1	
	SPI1	2.0	1.6	1.9	
	SYSCFG/VREFBUF/COMP	0.6	0.4	0.5	
	TIM1	8.3	6.9	7.9	
	TIM8	8.6	7.1	8.1	
	TIM15	4.1	3.4	3.9	
	TIM16	3.0	2.5	2.9	
	TIM17	3.0	2.4	2.9	
	USART1 independent clock domain	4.9	4.0	4.4	
	USART1 APB clock domain	1.5	1.3	1.7	
	All APB2 on	56.8	43.3	48.2	
ALL		256.8	189.6	215.5	

Table 60. I/O AC characteristics(1)(2) (continued)

Speed	Symbol	Parameter	Conditions	Min	Max	Unit
10	Fmax	Maximum frequency	C=50 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	50	MHz
			C=50 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	25	
			C=50 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	5	
			C=10 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	100(3)	
			C=10 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	37.5	
			C=10 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	5	
	Tr/Tf	Output rise and fall time	C=50 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	5.8	ns
			C=50 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	11	
			C=50 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	28	
			C=10 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	2.5	
			C=10 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	5	
			C=10 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	12	
11	Fmax	Maximum frequency	C=30 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	120(3)	MHz
			C=30 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	50	
			C=30 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	10	
			C=10 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	180(3)	
			C=10 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	75	
			C=10 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	10	
	Tr/Tf	Output rise and fall time	C=30 pF, 2.7 V≤V_{DDIOx}≤3.6 V	-	3.3	ns
			C=30 pF, 1.62 V≤V_{DDIOx}≤2.7 V	-	6	
			C=30 pF, 1.08 V≤V_{DDIOx}≤1.62 V	-	16	
Fm+	Fmax	Maximum frequency	C=50 pF, 1.6 V≤V_{DDIOx}≤3.6 V	-	1	MHz
	Tf	Output fall time(4)		-	5	ns

1. The I/O speed is configured using the OSPEEDRy[1:0] bits. The Fm+ mode is configured in the SYSCFG_CFGR1 register. Refer to the RM0392 reference manual for a description of GPIO Port configuration register.
2. Guaranteed by design.
3. This value represents the I/O capability but the maximum system frequency is limited to 80 MHz.
4. The fall time is defined between 70% and 30% of the output waveform accordingly to I^2C specification.

Table 68. ADC accuracy - limited test conditions 4(1)(2)(3) (continued)

Symbol	Parameter	Conditions(4)			Min	Typ	Max	Unit
THD	Total harmonic distortion	ADC clock frequency ≤ 26 MHz, 1.65 V ≤ V_{DDA} = VREF+ ≤ 3.6 V, Voltage scaling Range 2	Single ended	Fast channel (max speed)	-	-71	-69	dB
				Slow channel (max speed)	-	-71	-69	
			Differential	Fast channel (max speed)	-	-73	-72	
				Slow channel (max speed)	-	-73	-72	

1. Guaranteed by design.
2. ADC DC accuracy values are measured after internal calibration.
3. ADC accuracy vs. negative Injection Current: Injecting negative current on any analog input pins should be avoided as this significantly reduces the accuracy of the conversion being performed on another analog input. It is recommended to add a Schottky diode (pin to ground) to analog pins which may potentially inject negative current.
4. The I/O analog switch voltage booster is enable when V_{DDA} < 2.4 V (BOOSTEN = 1 in the SYSCFG_CFGR1 when V_{DDA} < 2.4 V). It is disable when V_{DDA} ≥ 2.4 V. No oversampling.

Table 70. DAC accuracy(1) (continued)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Gain	Gain error(5)	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ	-	-	±0.5	%
		DAC output buffer OFF CL ≤ 50 pF, no RL	-	-	±0.5	
TUE	Total unadjusted error	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ	-	-	±30	LSB
		DAC output buffer OFF CL ≤ 50 pF, no RL	-	-	±12	
TUECal	Total unadjusted error after calibration	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ	-	-	±23	LSB
SNR	Signal-to-noise ratio	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ 1 kHz, BW 500 kHz	-	71.2	-	dB
		DAC output buffer OFF CL ≤ 50 pF, no RL, 1 kHz BW 500 kHz	-	71.6	-	
THD	Total harmonic distortion	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ, 1 kHz	-	-78	-	dB
		DAC output buffer OFF CL ≤ 50 pF, no RL, 1 kHz	-	-79	-	
SINAD	Signal-to-noise and distortion ratio	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ, 1 kHz	-	70.4	-	dB
		DAC output buffer OFF CL ≤ 50 pF, no RL, 1 kHz	-	71	-	
ENOB	Effective number of bits	DAC output buffer ON CL ≤ 50 pF, RL ≥ 5 kΩ, 1 kHz	-	11.4	-	bits
		DAC output buffer OFF CL ≤ 50 pF, no RL, 1 kHz	-	11.5	-	

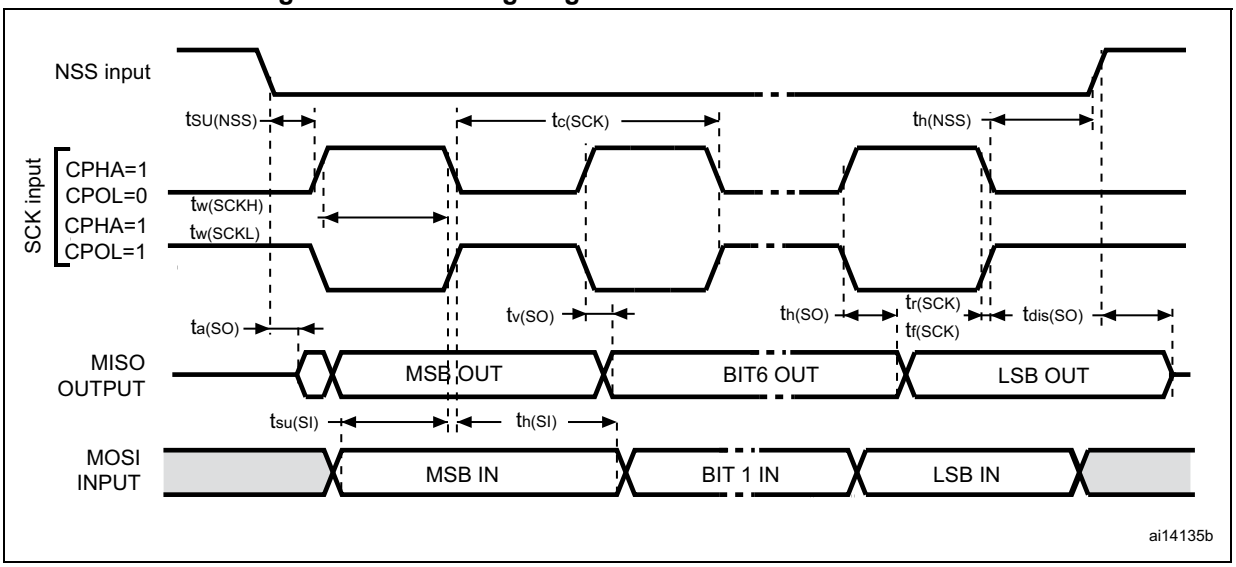
1. Guaranteed by design.
2. Difference between two consecutive codes - 1 LSB.
3. Difference between measured value at Code i and the value at Code i on a line drawn between Code 0 and last Code 4095.
4. Difference between the value measured at Code (0x001) and the ideal value.
5. Difference between ideal slope of the transfer function and measured slope computed from code 0x000 and 0xFFF when buffer is OFF, and from code giving 0.2 V and (V_{REF+} – 0.2) V when buffer is ON.

Table 73. OPAMP characteristics(1) (continued)

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{network}$	R2/R1 internal resistance values in PGA mode(5)	PGA Gain = 2		-	80/80	-	kΩ/kΩ
		PGA Gain = 4		-	120/ 40	-	
		PGA Gain = 8		-	140/ 20	-	
		PGA Gain = 16		-	150/ 10	-	
Delta R	Resistance variation (R1 or R2)	-		-15	-	15	%
PGA gain error	PGA gain error	-		-1	-	1	%
PGA BW	PGA bandwidth for different non inverting gain	Gain = 2	-	-	GBW/ 2	-	MHz
		Gain = 4	-	-	GBW/ 4	-	
		Gain = 8	-	-	GBW/ 8	-	
		Gain = 16	-	-	GBW/ 16	-	
en	Voltage noise density	Normal mode	at 1 kHz, Output loaded with 4 kΩ	-	500	-	nV/√Hz
		Low-power mode	at 1 kHz, Output loaded with 20 kΩ	-	600	-	
		Normal mode	at 10 kHz, Output loaded with 4 kΩ	-	180	-	
		Low-power mode	at 10 kHz, Output loaded with 20 kΩ	-	290	-	
$I_{DDA}(OPAMP)$(3)	OPAMP consumption from V_{DDA}	Normal mode	no Load, quiescent mode	-	120	260	µA
		Low-power mode		-	45	100	

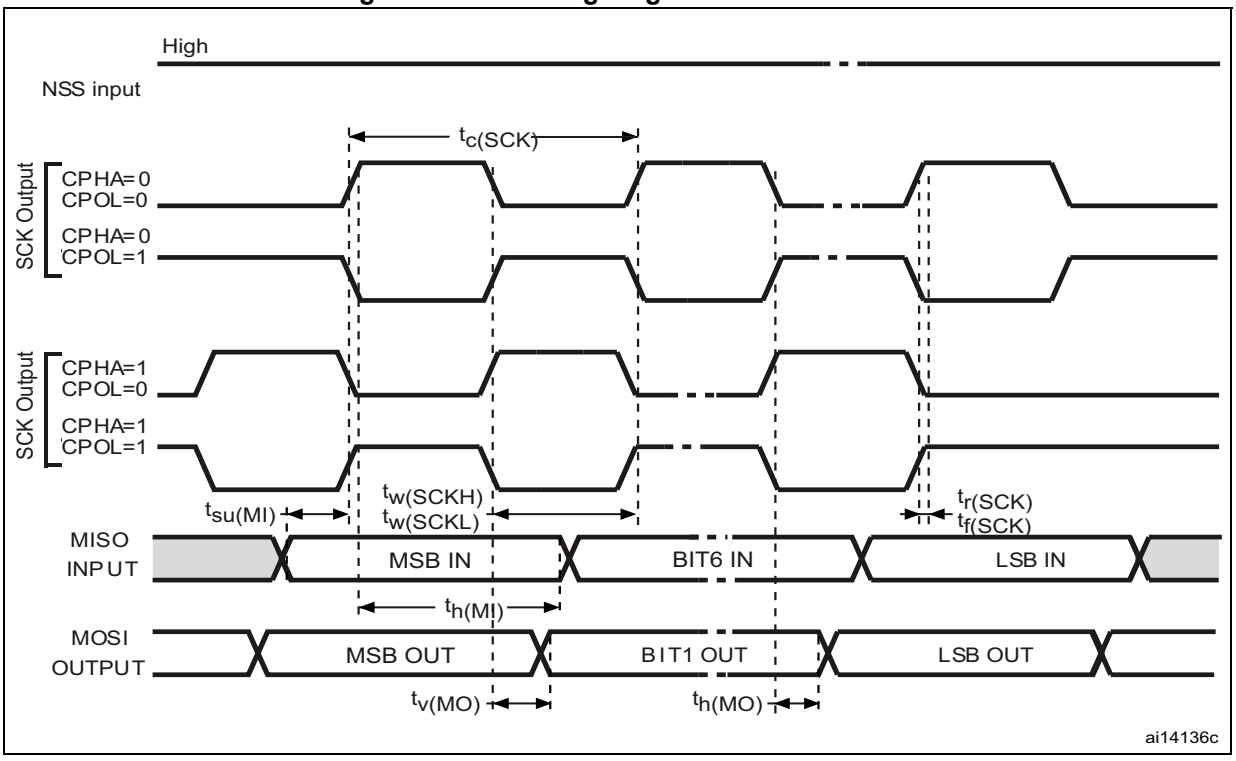
1. Guaranteed by design, unless otherwise specified.
2. The temperature range is limited to 0 °C-125 °C when V_{DDA} is below 2 V
3. Guaranteed by characterization results.
4. Mostly I/O leakage, when used in analog mode. Refer to I_{lkg} parameter in *Table 58: I/O static characteristics*.
5. R2 is the internal resistance between OPAMP output and OPAMP inverting input. R1 is the internal resistance between OPAMP inverting input and ground. The PGA gain =1+R2/R1

Figure 28. SPI timing diagram - slave mode and CPHA = 1



1. Measurement points are done at CMOS levels: 0.3 V_{DD} and 0.7 V_{DD}.

Figure 29. SPI timing diagram - master mode



1. Measurement points are done at CMOS levels: 0.3 V_{DD} and 0.7 V_{DD}.

Figure 41. Synchronous multiplexed PSRAM write timings

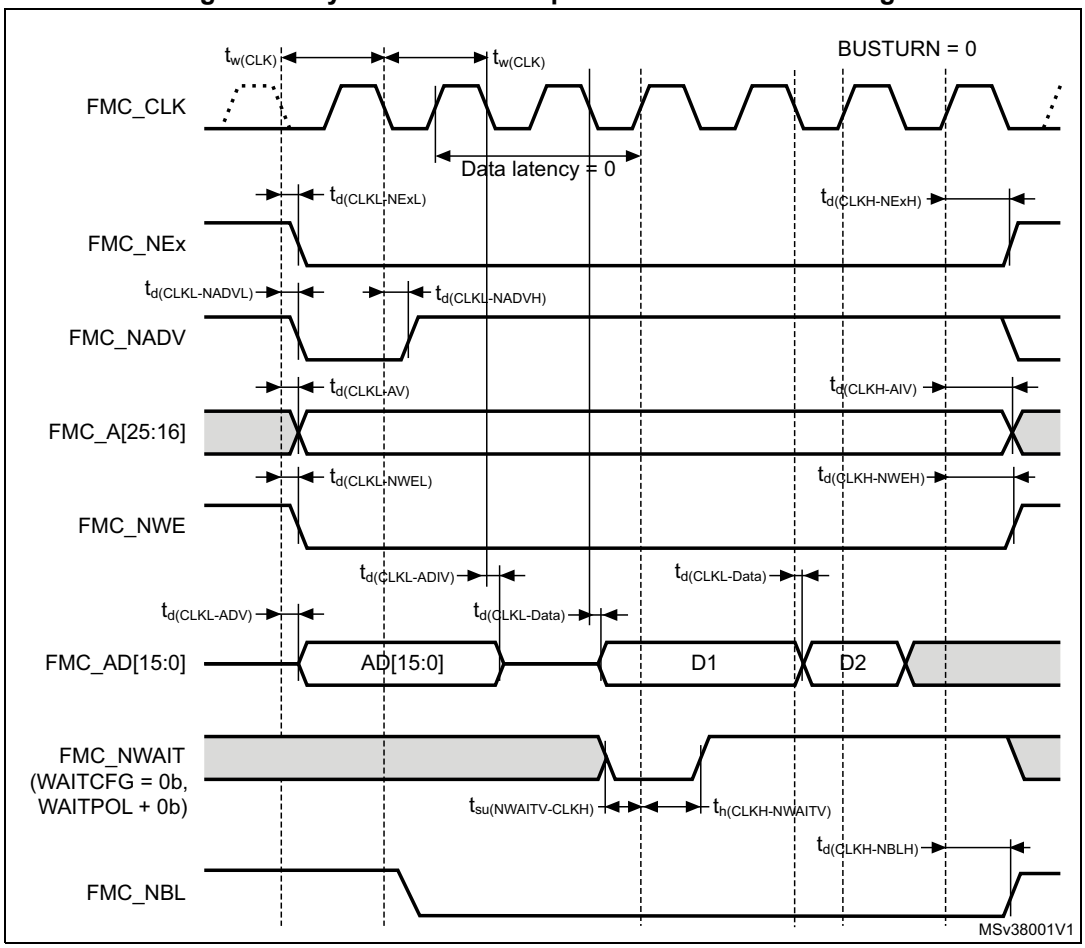


Figure 42. Synchronous non-multiplexed NOR/PSRAM read timings

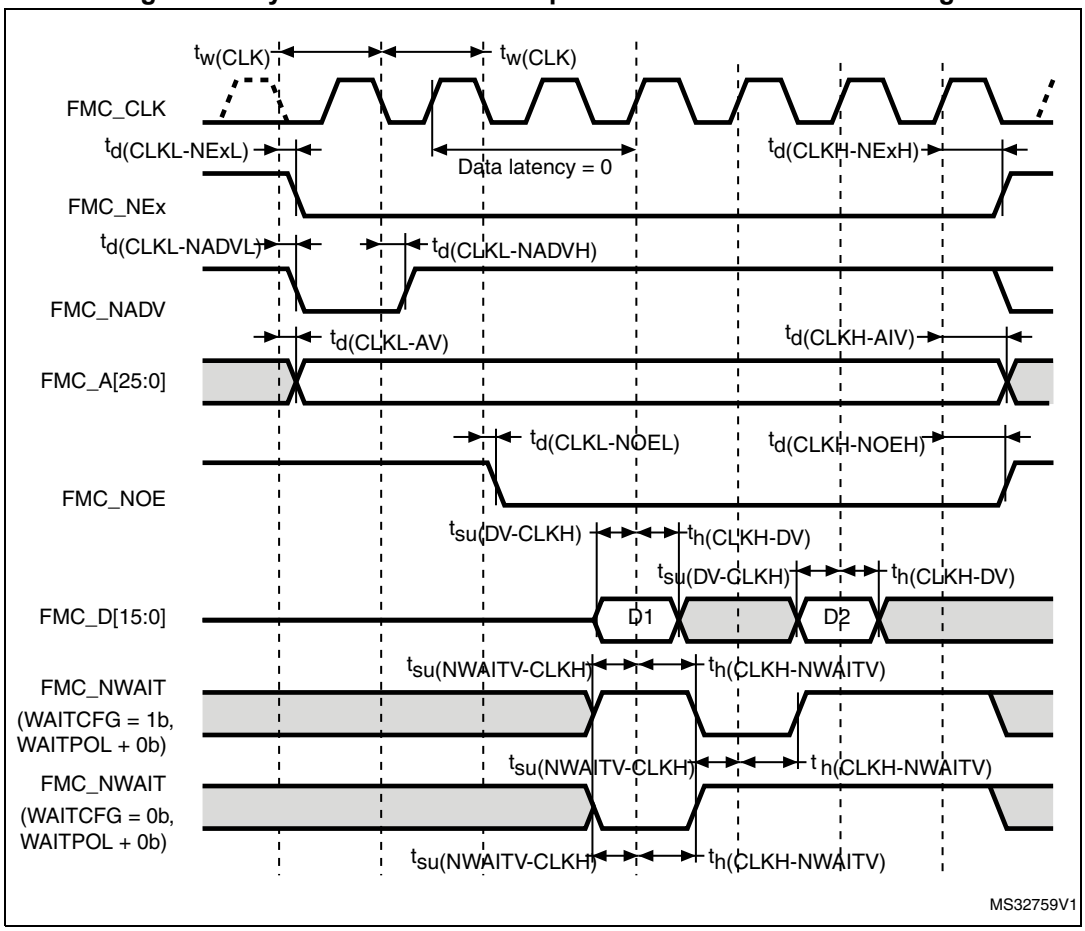


Table 98. Synchronous non-multiplexed NOR/PSRAM read timings(1)(2)

Symbol	Parameter	Min	Max	Unit
$t_{w(CLK)}$	FMC_CLK period	$2T_{HCLK}$	-	ns
$t_{d(CLKL-NExL)}$	FMC_CLK low to FMC_NEx low (x=0..2)	-	2.5	
$t_{d(CLKH-NExH)}$	FMC_CLK high to FMC_NEx high (x= 0…2)	T_{HCLK}-0.5	-	
$t_{d(CLKL-NADVL)}$	FMC_CLK low to FMC_NADV low	-	2	
$t_{d(CLKL-NADVH)}$	FMC_CLK low to FMC_NADV high	0.5	-	
$t_{d(CLKL-AV)}$	FMC_CLK low to FMC_Ax valid (x=16…25)	-	3.5	
$t_{d(CLKH-AIV)}$	FMC_CLK high to FMC_Ax invalid (x=16…25)	T_{HCLK}	-	
$t_{d(CLKL-NOEL)}$	FMC_CLK low to FMC_NOE low	-	2	
$t_{d(CLKH-NOEH)}$	FMC_CLK high to FMC_NOE high	T_{HCLK}-0.5	-	
$t_{su(DV-CLKH)}$	FMC_D[15:0] valid data before FMC_CLK high	0	-	
$t_{h(CLKH-DV)}$	FMC_D[15:0] valid data after FMC_CLK high	5	-	
$t_{su(NWAIT-CLKH)}$	FMC_NWAIT valid before FMC_CLK high	0	-	
$t_{h(CLKH-NWAIT)}$	FMC_NWAIT valid after FMC_CLK high	4	-	

8 Part numbering

Table 108. STM32L471xx ordering information scheme

Example: STM32 L 471 R G T 6 TR

Device family

STM32 = ARM® based 32-bit microcontroller

Product type

L = ultra-low-power

Device subfamily

471: STM32L471xx

Pin count

R = 64 pins

V = 100 pins

Q = 132 pins

Z = 144 pins

Flash memory size

E = 512 KB of Flash memory

G = 1 MB of Flash memory

Package

T = LQFP ECOPACK®2

I = UFBGA ECOPACK®2

Temperature range

6 = Industrial temperature range, -40 to 85 °C (105 °C junction)

7 = Industrial temperature range, -40 to 105 °C (125 °C junction)

3 = Industrial temperature range, -40 to 125 °C (130 °C junction)

Packing

TR = tape and reel

xxx = programmed parts